

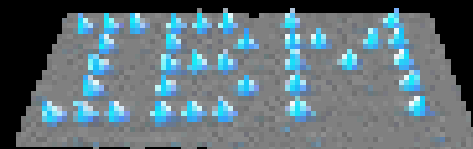


Corporate Environmental Affairs

Nanotechnology as a Tool to Advance Pollution Prevention in the Semiconductor/IT Industry

Airgap Microprocessors: Directed Self-Assembly

Arthur Fong, PhD



US EPA Pollution Prevention
through Nanotechnology Conference

September 25-26, 2007
Arlington, VA

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Presentation Outline

- **Overview of nanotechnology in semiconductor/IT industry**
- **Nanotechnology - Tool to enhance performance and advance pollution prevention**
 - Airgap microprocessors: directed self-assembly

Nanotechnology – Hype vs. Substance - 1



- **\$1 Trillion business by 2011-2015 (NSF, 2001)**
- **\$2.6 Trillion of manufactured goods by 2014 (Lux Research, 2006)**

Nanotechnology – Hype vs. Substance - 2

- “Nano”? products everywhere



“Magic Nano” glass and ceramic tile sealant aerosol spray



Pentel - Nanocapsule-imbued scented pencil lead

Aromatherapy + nanotechnology



Nanotechnology – Hype vs. Substance - 3

- **Applied use currently limited, but ramping up fast**
 - Project on Emerging Nanotechnologies,
Nanotechnology Consumer Products Inventory
- **Nanoelectronics leads nanotechnology commercialization**



Nanoelectronics Market Data and Forecast

- **2005 Worldwide market ~ US \$60 billion**
- **2010 Worldwide projection ~ US \$250 billion**

- **Nanoelectronics**
 - Displays – e.g., field emission display
 - MEMS/NEMS – e.g., nano-mechanical data storage
 - Optoelectronics/sensors – e.g., photonic devices
 - Semiconductors – e.g., transistors and interconnects
 - Hard-disk storage – e.g., magnetic storage

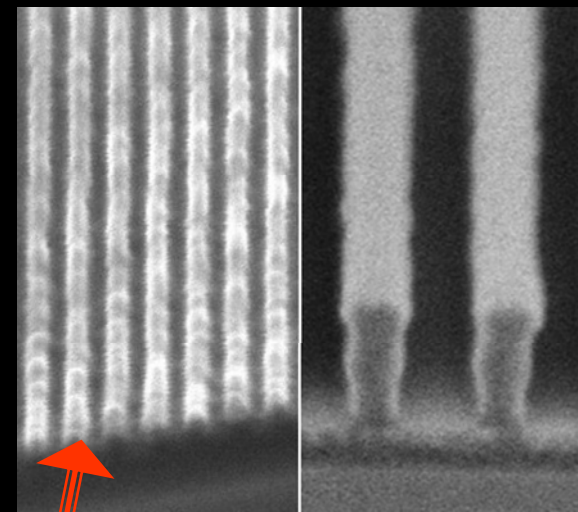
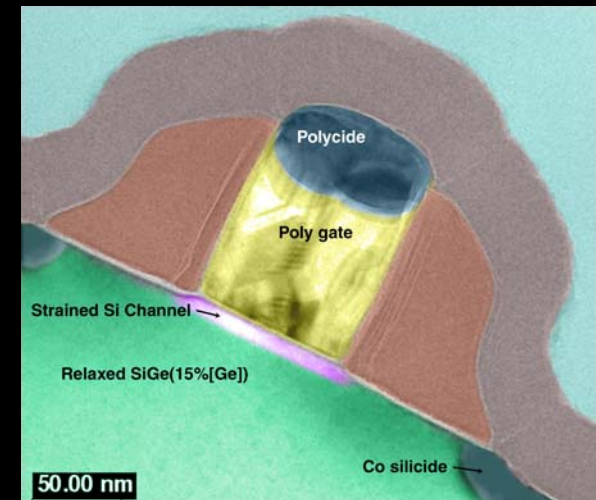
Nanotechnology is Not New in Semiconductor/IT Industry

■ Early stages

- 100 nm Bipolar transistor base (ca. 1970)
- 100 nm CMOS (complementary metal oxide semiconductor) gate oxide (ca. 1970)

■ More recently

- Transistor physical gate length ~ 70 nm (2000)
- 90-nm Technology node – gate oxide of 1.2 nm, about 4 atomic-layers thick (2003)
- Electron beam lithography 40-70 nm

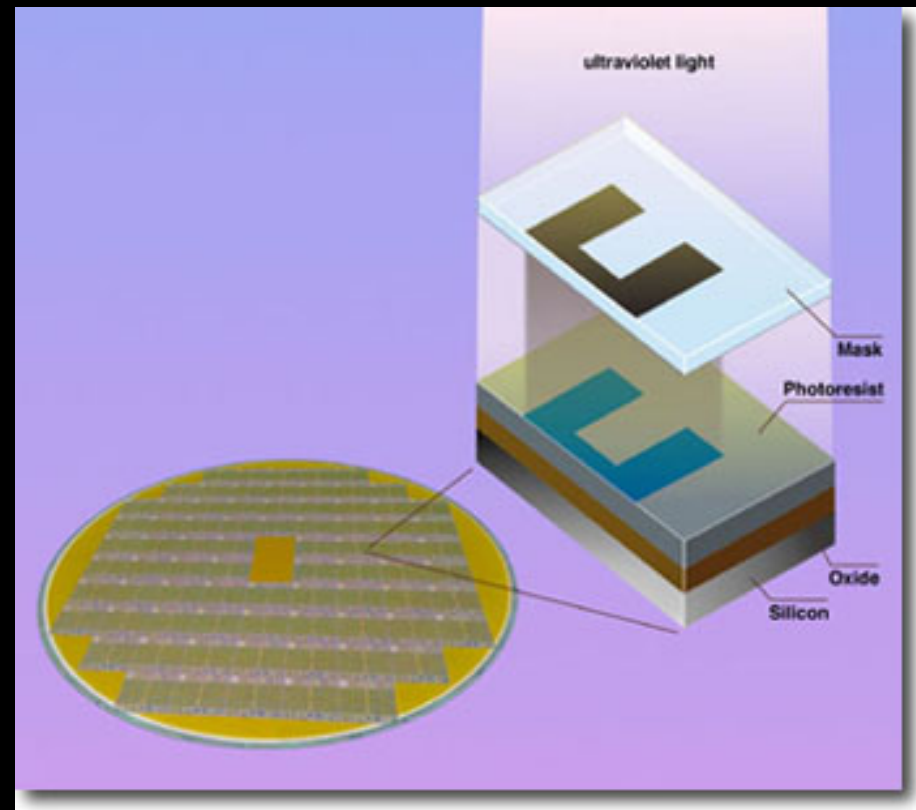


29.9 nm, Deep-UV optical lithography

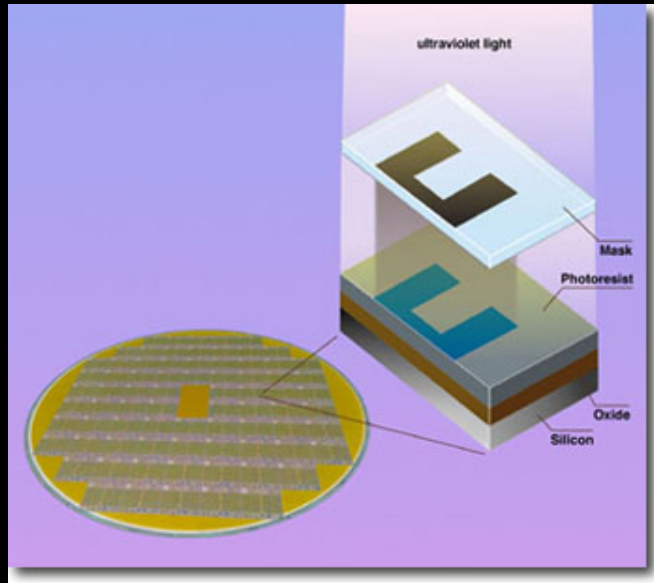
Current Semiconductor/IT Nanotechnology - Photolithography

- **Masking**
- **Etching**

- **Examples of chemicals in photolithography**
 - Photoresist (photoactive organic polymers)
 - Developers (tetramethyl ammonium hydroxide)
 - Solvents and cleaning agents
 - Etching (acids, chlorine)
 - Stripping (acids, alkalines)

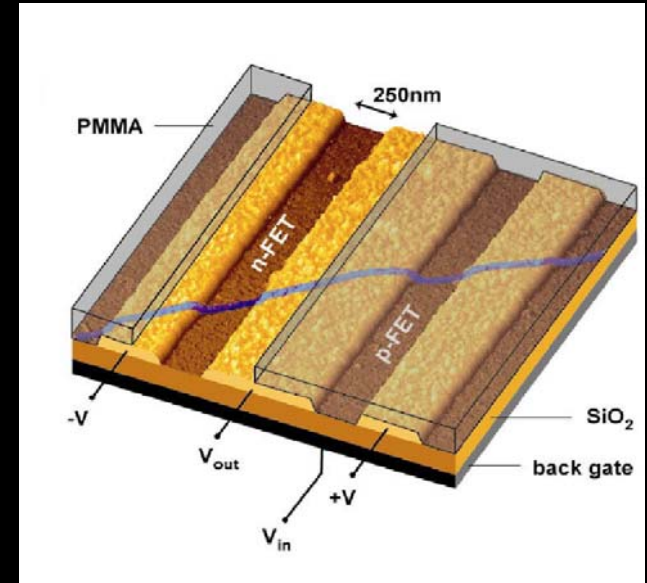


Traditional Semiconductor/IT Nanotechnology and Engineered Nanomaterials



■ Semiconductor/IT nanotechnology

- Minimum feature size of devices - at nanoscale for decades
- Photolithography
- “Does not present any unique hazards” (Royal Society & Royal Academy of Engineering, 2004)



■ Engineered nanomaterials

- Discrete manufactured nanoparticles, nanotubes, and other nanomaterials
- ## ■ Nanomaterials fixed within products



Nanotechnology – A Critical Key to Future Development of Semiconductor/IT Industry

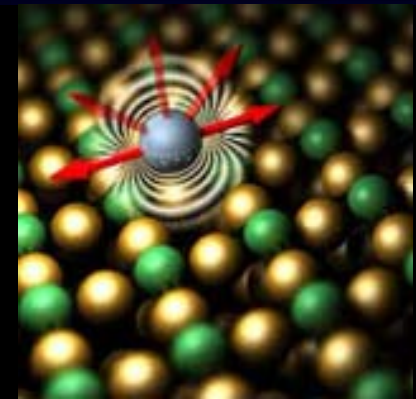
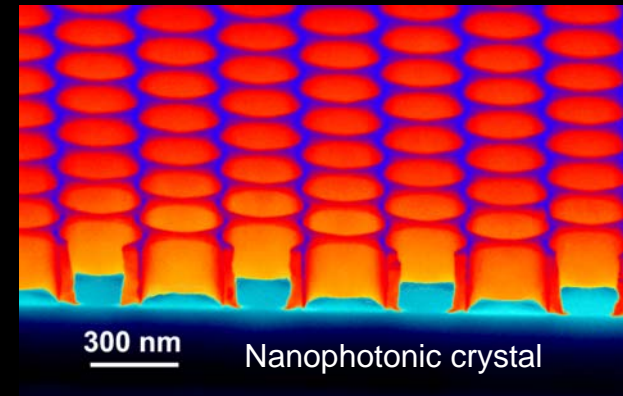
(International Technology Roadmap for Semiconductors, 2005, 2006)

- **Potential solutions to technical challenges**
 - Approaching limits of current manufacturing processes and materials
- **Potential solutions to business challenges**
 - Escalating fab costs
 - Opportunity for diversification
- **Tremendous opportunity for environmental, health, and safety benefits – pollution prevention**
 - Energy/resource conservation – manufacturing/processes
 - Waste minimization, e.g., self-assembly
 - Energy efficient products

Examples of IBM Nanotechnology R&D

Performance Enhancement and Pollution Prevention

- **By 2010, the codified information base of the world is expected to double every 11 hours**
- **Nanophotonics – Control over light signal**
 - Optical Networks
- **Atomic magnetism – single-atom data storage (08/2007)**
- **Single-molecule switching – molecular computers comprising of just a few molecules (08/2007)**
- **Airgap microprocessors (05/2007)**
 - Directed self-assembly





Self-Assembly: How Will We Manufacture at the Nanoscale?

Two visions of nanofabrication:

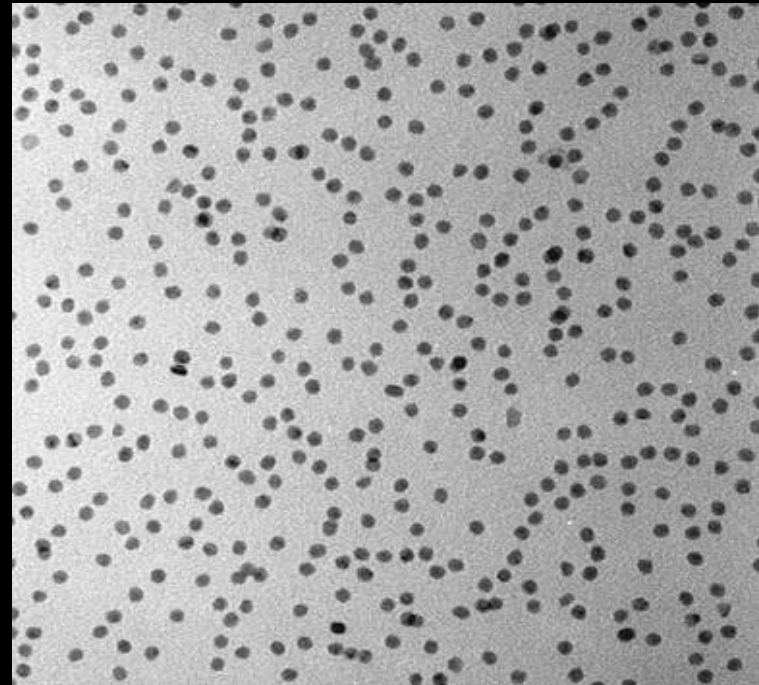
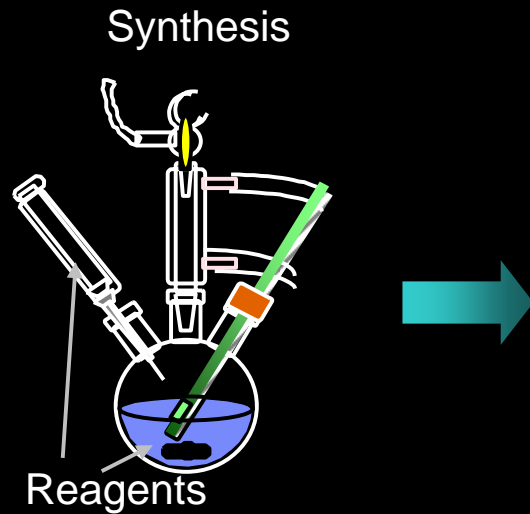
- **“Old”**
- **Top down**
- **Lithography**
- **Digital**
- **Depend on low error rates**
- **Molecular assemblers**
- **“New”**
- **Bottom up**
- **Chemical synthesis**
- **Analog**
- **Tolerate high error rates**
- **Self-assembly**

This is a false dichotomy!

T. Theis, IBM Research



Allowing a Few Components to Approach Equilibrium Will Produce Only Simple Structures

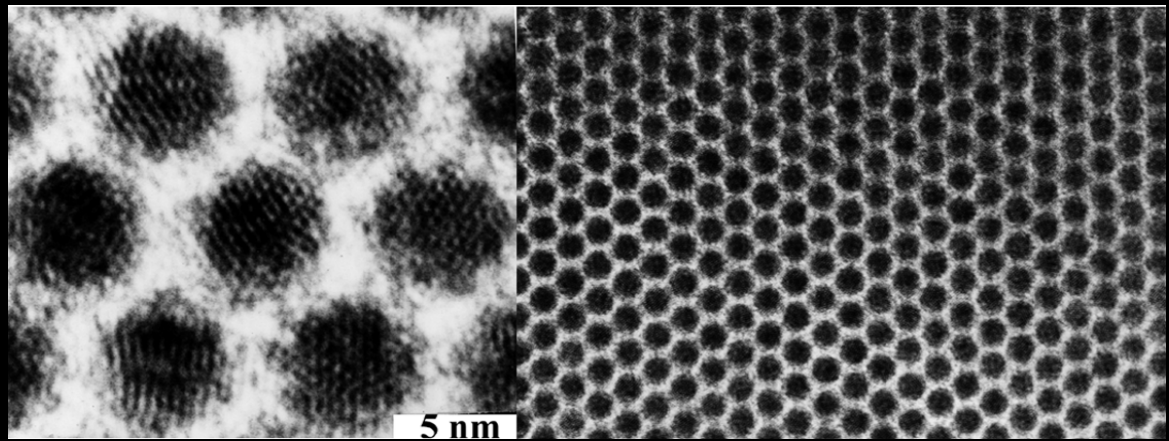
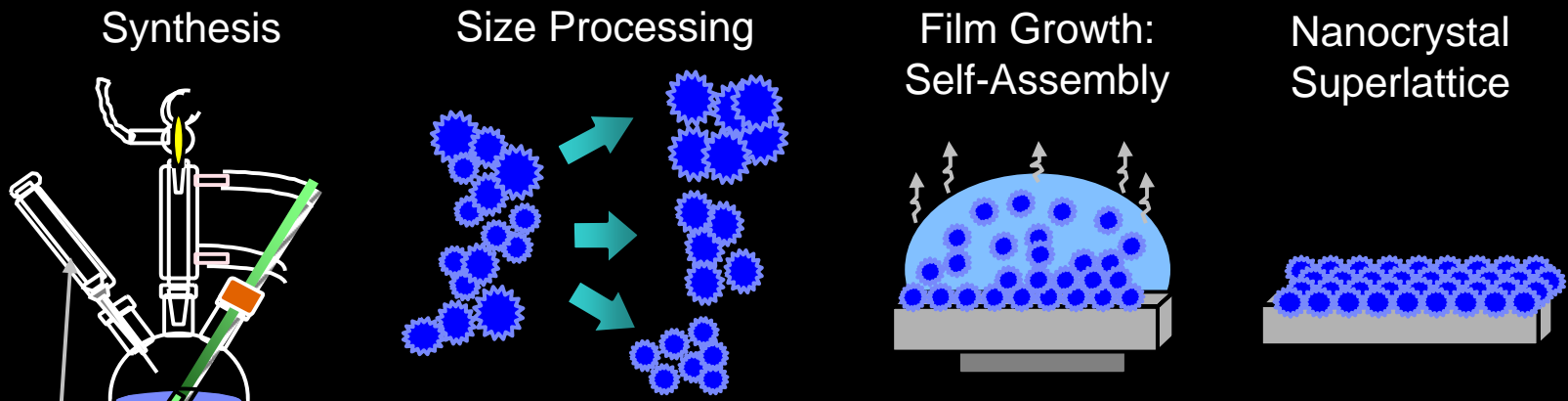


T. Theis, IBM Research



“Guiding” or “Directing” the Equilibration Process:

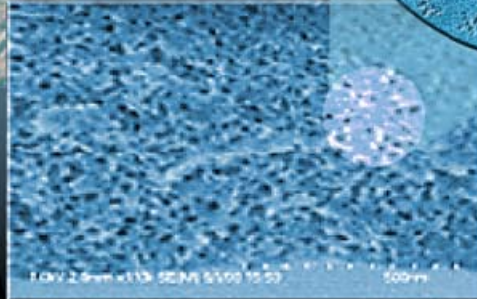
Semiconductor Nanocrystals



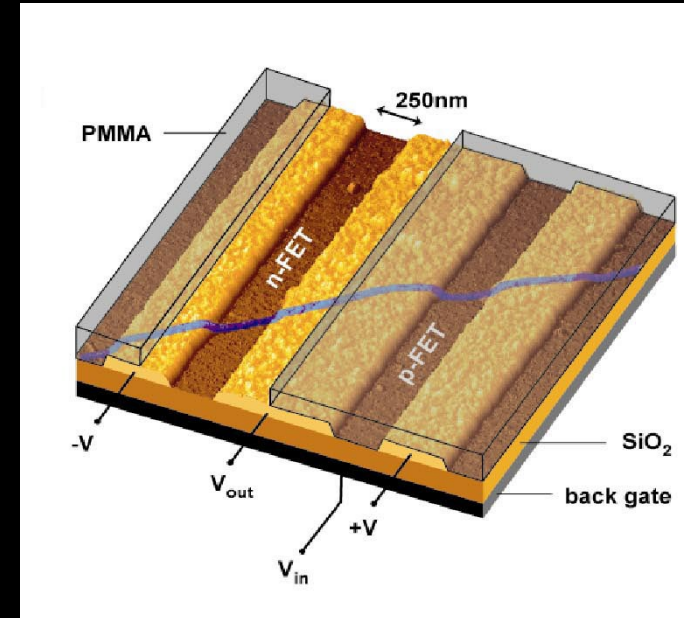
T. Theis, IBM Research

Goal: Incorporate Nanoscale Components in IT Systems

Poromer (dendritic polymer)



Porous dielectric for on-chip wiring



- IBM - World's first single-molecule (carbon nanotube) computer circuit
- Leading to new class of computers
 - Smaller
 - Faster
 - Consume less power

Directed Self-Assembly Nanotechnology to Create Airgap Microprocessors (05/2007)

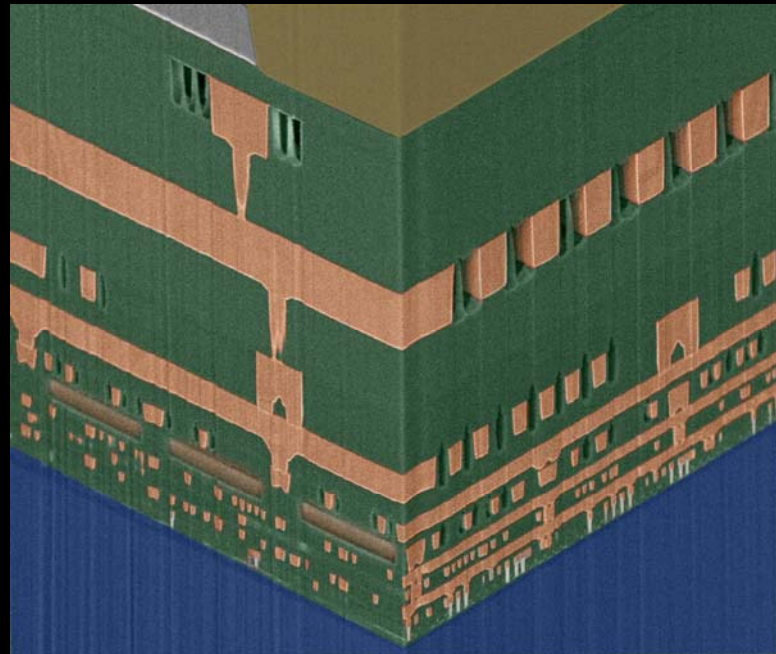
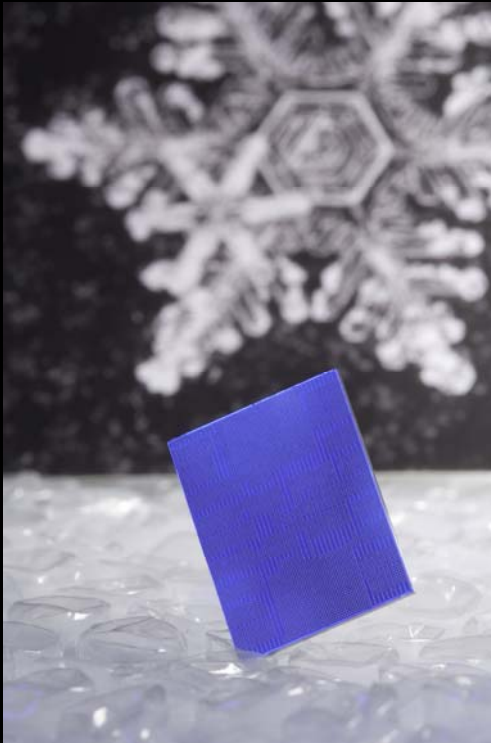
- **Current process – nanoscale wires in microprocessors insulated with glass-like material**
- **Airgap - vacuum gaps to insulate nanoscale wires**
- **Significant enhancement of performance**
 - Equivalent of two generations of Moore's Law improvement



IBM Fellow Dan Edelstein

Airgap: Directed Self-Assembly

- **Nature's ability to form intricate patterns (snowflakes, sea shells)**
 - Mix of compounds/polymers
 - Pour onto silicon wafer
 - Bake – directed self-assembly
 - Trillions of uniform 20-nm holes (vacuum “airgaps”) in wafer



Airgap: Directed Self-Assembly Animation





Breakthrough of Directed Self-Assembly Airgap Nanotechnology

- **Current process – lithography**

- Masking
- Etching

- **Examples of chemicals in photolithography**

- Photoresist (photoactive organic polymers)
- Developers (tetramethyl ammonium hydroxide)
- Solvents and cleaning agents
- Etching (acids, chlorine)
- Stripping (acids, alkalines)

- **Self-assembly - 20-nm vacuum holes**

- 5x smaller than lithography
- Not possible with lithography

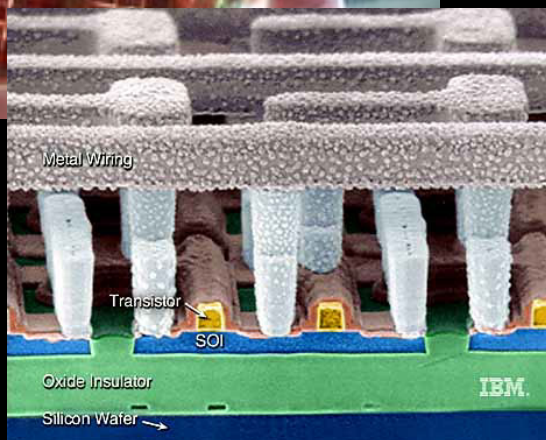
- **Manufacturing**

- Resource and energy conservation
- Waste minimization

- **Product**

- 35% Faster
- 15% Less energy consumption

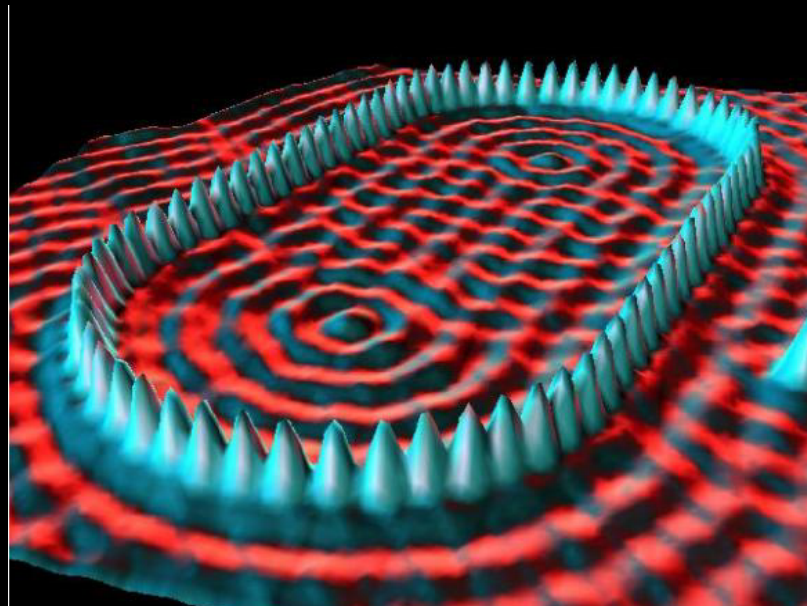
Why Would Even Small Gains in Energy Efficiency Result in Major Advances in Pollution Prevention?



■ Last year the world produced more transistors (and at a lower cost) than grains of rice

Thank you

- **Contact information**
 - fonga@us.ibm.com



Using the scanning tunneling microscope (STM), electron formations can be viewed. Above, electrons are surrounded by 48 iron atoms, individually positioned with the same STM used to image them - IBM Almaden Research Center.